

APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	METHOD AND DEVICE FOR CUTTING WIRE FORMED ON SEMICONDUCTOR SUBSTRATE
Application Type :	regular, utility
Attorney Docket Number :	040103
Correspondence address:	
Customer Number:	23850
	
Priority Data:	
Doc.No: 2003-361072; Country -JP ; Date: 2003-10-21 us-priority-claimed	
Inventors Information:	
<u>Inventor 1:</u>	
Applicant Authority Type:	Inventor
Citizenship:	JP
Given Name:	Yukio
Family Name:	MARUTA
Residence:	
City of Residence:	Kasugai
Country of Residence:	JP
Address-1 of Mailing Address:	c/o FUJITSU VLSI LIMITED
Address-2 of Mailing Address:	1844-2, Kozoji-cho 2-chome
City of Mailing Address:	Kasugai-shi, Aichi
State of Mailing Address:	
Postal Code of Mailing Address:	487-0013
Country of Mailing Address:	JP
Phone:	
Fax:	
E-mail:	
<u>Inventor 2:</u>	
Applicant Authority Type:	Inventor
Citizenship:	JP

Given Name:	Kinichi
Family Name:	MIZUNO
Residence:	
City of Residence:	Kawasaki
Country of Residence:	JP
Address-1 of Mailing Address:	c/o FUJITSU LIMITED
Address-2 of Mailing Address:	1-1, Kamikodanaka 4-chome, Nakahara-ku
City of Mailing Address:	Kawasaki-shi, Kanagawa
State of Mailing Address:	
Postal Code of Mailing Address:	211-8588
Country of Mailing Address:	JP
Phone:	
Fax:	
E-mail:	

Assignee 1:

Organization Name:	FUJITSU LIMITED
Address-1 of Mailing Address:	1-1, Kamikodanaka 4-chome
Address-2 of Mailing Address:	Nakahara-ku
City of Mailing Address:	Kawasaki-shi, Kanagawa
State of Mailing Address:	
Postal Code of Mailing Address:	211-8588
Country of Mailing Address:	JP
Phone:	
Fax:	
E-mail:	